CD54AC161 ... F PACKAGE CD74AC161 ... E OR M PACKAGE

(TOP VIEW)

CLR

CLK 2

A 3

В 🛛 4

C 🛛 5

 $D \Pi 6$ 

ENP 7

GND 8

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16 VCC

15 RCO

14 🛛 QA

13 Q<sub>B</sub>

12 Q<sub>C</sub>

11 Q<sub>D</sub>

10 ENT

9 I LOAD

- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection per MIL-STD-883, Method 3015

description/ordering infor	rmation

The 'AC161 devices are 4-bit binary counters. These synchronous, presettable counters feature an internal carry look-ahead for application in

high-speed counting These devices are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. Presetting is synchronous; therefore, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15, with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

The counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or LOAD) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

TA	PAC	KAGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC161E	CD74AC161E
–55°C to 125°C	SOIC – M	Tube	CD74AC161M	AC161M
-55 C 10 125 C	30IC - M	Tape and reel	CD74AC161M96	ACTOTIN
	CDIP – F	Tube	CD54AC161F3A	CD54AC161F3A

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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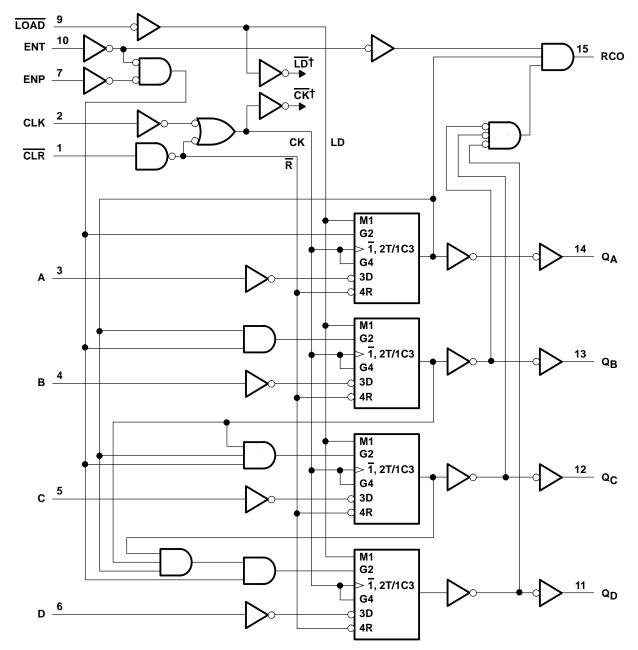
_								
		IN	IPUTS			OUT	PUTS	FUNCTION
CLR	CLK	ENP	ENT	LOAD	A,B,C,D	FUNCTION		
L	Х	Х	Х	Х	Х	Reset (clear)		
н	$\uparrow$	Х	Х	I	I	L	L	Parallel load
н	$\uparrow$	Х	Х	I	h	Н	Note 1	Farallerioau
н	$\uparrow$	h	h	h	Х	Count	Note 1	Count
н	Х	I	Х	h	Х	q <sub>n</sub>	Note 1	Inhibit
н	Х	Х	I	h	Х	q <sub>n</sub>	L	

H = high level, L = low level, X = don't care, h = high level one setup time prior to the CLK low-to-high transition, I = low level one setup time prior to the CLK low-to-high transition, q = the state of the referenced output prior to the CLK low-to-high transition, and  $\uparrow$  = CLK low-to-high transition.

NOTE 1: The RCO output is high when ENT is high and the counter is at terminal count (HHHH).



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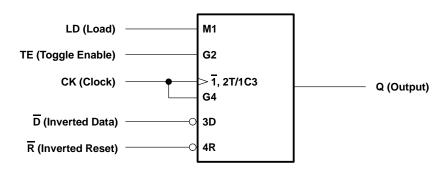
logic diagram (positive logic)

<sup>†</sup> For simplicity, routing of complementary signals  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

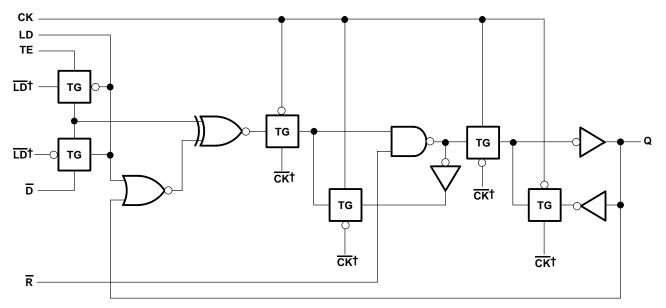


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#### logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)



<sup>†</sup> The origins of  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  are shown in the logic diagram of the overall device.

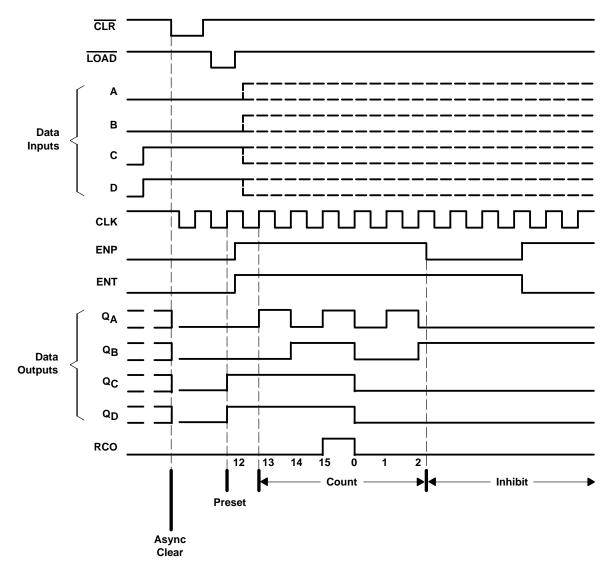


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#### typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ V or $V_I > V_{CC}$ ) (see Note 2)	
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 2)	
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 4)

			T <sub>A</sub> = 2	25°C	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
	Low-level input voltage	V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
VIL		$V_{CC} = 3 V$		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
٧O	Output voltage		0	VCC	0	VCC	0	VCC	V
IOH	High-level output current			-24		-24		-24	mA
IOL	Low-level output current			24		24		24	mA
A#/A	Innut transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V		50		50		50	
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC}$ = 3.6 V to 5.5 V		20		20		20	ns

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST CON	Vcc	T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT		
				MIN MA	XN	MIN	MAX	MIN	MAX		
			1.5 V	1.4		1.4		1.4			
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9			
			4.5 V	4.4		4.4		4.4			
VOH	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V	
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8			
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V	-	3	.85		-			
		I <sub>OH</sub> = -75 mA†	5.5 V	-		-		3.85			
			1.5 V	0	.1		0.1		0.1		
		I <sub>OL</sub> = 50 μA	3 V	0	.1		0.1		0.1		
			4.5 V	0	.1		0.1		0.1		
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 12 mA	3 V	0.3	86		0.5		0.44	V	
		I <sub>OL</sub> = 24 mA	4.5 V	0.3	86		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V		-		1.65		-		
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V		-		-		1.65		
lj	$V_I = V_{CC} \text{ or } GND$		5.5 V	±0	.1		±1		±1	μA	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μA	
Ci					0		10		10	pF	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			Vcc	–55° 125		–40°( 85°		UNIT
				MIN	MAX	MIN	MAX	
			1.5 V		7		8	
<sup>f</sup> clock	Clock frequency		$3.3~\text{V}\pm0.3~\text{V}$		64		73	MHz
			$5~V\pm0.5~V$		90		103	
			1.5 V	69		61		
		CLK high or low	$3.3~\text{V}\pm0.3~\text{V}$	7.7		6.8		
tw	Pulse duration		$5~V\pm0.5~V$	5.5		4.8		
۱W	Pulse duration		1.5 V	63		55		ns
		CLR low	$3.3~\text{V}\pm0.3~\text{V}$	7		6.1		
			$5~V\pm0.5~V$	5		4.4		
			1.5 V	63		55		
	Setup time, before CLK↑	A, B, C, or D	$3.3~\text{V}\pm0.3~\text{V}$	7		6.1		ns
			$5 \text{ V} \pm 0.5 \text{ V}$	5		4.4		
t <sub>su</sub>			1.5 V	75		66	ns	ns
		LOAD	$3.3~\text{V}\pm0.3~\text{V}$	8.4		7.4		
			$5~V\pm0.5~V$	6		5.3		1
			1.5 V	0		0		
		A, B, C, or D	$3.3$ V $\pm$ 0.3 V	0		0		
<b>4</b> .	Hold time offer CLK <sup>↑</sup>		$5~V\pm0.5~V$	0		0		~~
th	Hold time, after CLK↑		1.5 V	0		0		ns
		ENP or ENT	$3.3~\text{V}\pm0.3~\text{V}$	0		0		
			$5~V\pm0.5~V$	0		0		
			1.5 V	75		66		
trec	Recovery time, $\overline{CLR}^{\uparrow}$ before $CLK^{\uparrow}$	$3.3$ V $\pm$ 0.3 V	8.4		7.4		ns	
			$5 \text{ V} \pm 0.5 \text{ V}$	6		5.3		



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# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

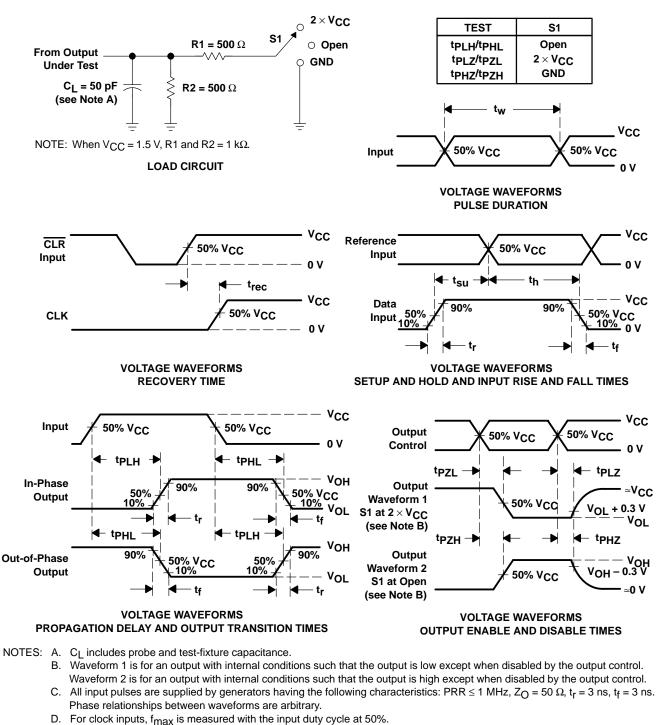
PARAMETER	FROM (INPUT)	TO (OUTPUT)	Vcc	–55° 125		–40° 85°		UNIT
	(INFOT)	(001-01)		MIN	MAX	MIN	MAX	
			1.5 V	7		8		
f <sub>max</sub>			$3.3~\text{V}\pm0.3~\text{V}$	64		73		MHz
			$5~\text{V}\pm0.5~\text{V}$	90		103		
			1.5 V	-	209	-	190	
		RCO	$3.3~\text{V}\pm0.3~\text{V}$	6	23.4	6	21	
	CLK		$5~V\pm0.5~V$	4.3	16.7	4.3	15.2	
	CLK		1.5 V	-	207	-	188	
		Any Q	$3.3~\text{V}\pm0.3~\text{V}$	5.9	23.1	5.9	21	
			$5~V\pm0.5~V$	4.2	16.5	4.2	15	
	ENT	RCO	1.5 V	-	129	-	117	
<sup>t</sup> pd			$3.3~\text{V}\pm0.3~\text{V}$	3.6	14.4	3.7	13.1	ns
			$5~V\pm0.5~V$	2.6	10.3	2.7	9.4	
			1.5 V	-	207	-	188	
		Any Q	$3.3~\text{V}\pm0.3~\text{V}$	5.9	23.1	5.9	21	
			$5~V\pm0.5~V$	4.2	16.5	4.2	15	
	CLR		1.5 V	_	207	-	188	
		RCO	$3.3~\text{V}\pm0.3~\text{V}$	5.9	23.1	5.9	21	1
			$5~V\pm0.5~V$	4.2	16.5	4.2	15	

### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	66	pF

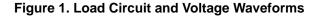


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PARAMETER MEASUREMENT INFORMATION

- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpzL and tpzH are the same as ten.
- H. tpl  $_{7}$  and tpH $_{7}$  are the same as t<sub>dis</sub>.
- I. All parameters and waveforms are not applicable to all devices.







#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CD54AC161F3A	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC161F3A	Samples
CD74AC161E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC161E	Samples
CD74AC161M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC161M	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE OPTION ADDENDUM

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF CD54AC161, CD74AC161 :

- Catalog : CD74AC161
- Military : CD54AC161

NOTE: Qualified Version Definitions:

#### Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

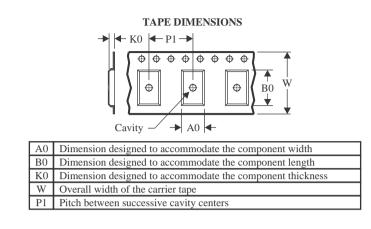


TEXAS

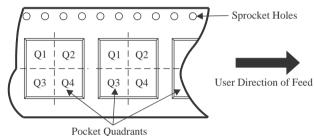
NSTRUMENTS

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC161M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

6-Apr-2024



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC161M96	SOIC	D	16	2500	340.5	336.1	32.0

#### TEXAS INSTRUMENTS

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6-Apr-2024

#### TUBE



#### - B - Alignment groove width

\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74AC161E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC161E	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

# D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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